MAX685

ABSOLUTE MAXIMUM RATINGS

V _{DD} , VP to GND	0.3V to +6V
PGND to GND	0.3V to +0.3V
V _{DD} to VP	0.3V to +0.3V
LXN, POK to GND	0.3V to +30V
LXP to V _{DD}	
REF, SEQ, SHDN to GND	0.3V to (V _{DD} + 0.3V)
FBP, FBN, SYNC to GND	0.3V to +6V

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{DD} = VP = 5V, **T_A = 0°C to +85°C** unless otherwise noted. Typical values are at T_A = +25°C.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Input Voltage Range	V _{DD} = VP	2.7		5.5	V
Positive Output Voltage Range		VP		24	V
Negative Output Voltage Range	V _{DD} = 5.5V (Note 1)	-9		-1.27	V
Output Current	V _{DD} = 4.5V, V _{OUT+} ≥ 14.25V, V _{OUT-} ≤ -7.125V, Figure 3	10			mA
LX Current Limit	$T_A = +25^{\circ}C$		440		mA
LXP, LXN On-Resistance	$V_{DD} = 4.5 V$		0.6	2	Ω
Quiescent Current	SYNC = V _{DD}		0.8		mA
Idle Quiescent Current	$V_{FBP} = 1.35V, V_{FBN} = -0.1V$		300	500	μA
Line Regulation	$V_{DD} = 4.5V$ to 5.5V		0.2		%/V
Load Regulation	$I_{OUT} = 0$ to 10mA, C1 = 10 μ F		0.13		%/mA
Output Voltage Ripple	$C3 = C4 = 10\mu F$, $I_{LOAD} = 5mA$		30		mVp-p
SHUTDOWN (SHDN)					•
Shutdown Supply Current	SYNC = SEQ = \overline{SHDN} = GND		0.1	10	μA
UNDERVOLTAGE LOCKOUT					I
UVLO Threshold	V _{DD} = rising	2.35	2.5	2.65	V
UVLO Hysteresis			50		mV
REFERENCE VOLTAGE					
VREF Output Voltage	No load	1.23	1.250	1.27	V
VREF Load Regulation	0 < I _{REF} < 50μA		-2		mV
FB INPUTS		·			
FBP Threshold Voltage	No load	1.21	1.24	1.27	V
FBN Threshold Voltage	No load	-16	10	36	mV
FBP, FBN Input Leakage Current			±0.01	±0.1	μA
LOGIC INPUTS (SEQ, SHDN, SYN	C)				
Logic-Low Input	$2.7V < V_{DD} < 5.5V$		0	.3 x Vdd	V
Logic-High Input	$2.7V < V_{DD} < 5.5V$	0.7 x V _{DD})		V
Input Bias Current			0.1	1	μA



ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = VP = 5V, T_A = 0^{\circ}C \text{ to } +85^{\circ}C \text{ unless otherwise noted. Typical values are at }T_A = +25^{\circ}C.)$

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
SYNC INPUT		ľ			
Sync Frequency Range (external)		200		480	kHz
	SYNC = GND	175	220	265	kHz
Oscillator Frequency (internal)	SYNC = V _{DD}	320	400	480	KHZ
POK COMPARATORS					
FBP POK Threshold	FBP rising	1.090	1.122	1.150	V
FBN POK Threshold	FBN falling	54	79	108	mV
POK Output Low Voltage	I _{POK} = 2mA			0.4	V
POK Output Off Current	V _{POK} = 10V			1	μA

ELECTRICAL CHARACTERISTICS

(V_{DD}, VP = 5V, $T_A = -40^{\circ}C$ to $+85^{\circ}C$ unless otherwise noted.) (Note 2)

put Voltage Range $V_{DD} = VP$ 2.7psitive Output Voltage Range $V_{DD} = 5.5V$ (Note 1)-9egative Output Voltage Range $V_{DD} = 5.5V$ (Note 1)-9aximum Output Current $V_{IN} = 4.5V$, $V_{OUT+} \ge 14.25V$, $V_{OUT-} \le -7.125V$, Figure 310le Quiescent CurrentSYNC = GND10AUTDOWNnutdown Supply CurrentSYNC = SEQ = SHDN = GNDNDERVOLTAGE LOCKOUT/LO Threshold $V_{DD} = rising$ 2.35B Threshold VoltageNo load1.205NN Inteshold VoltageNo load1.205SN Threshold VoltageNo load1.205OGIC INPUTS (SEQ, SHDN, SYNC)regic-Low Input2.7V < V_{DD} ≤ 5.5V0.7 x V_{DD}OGIC INPUTS (SEQ, SHDN, SYNC)regic-Low Input2.7V < V_{DD} ≤ 5.5V0.7 x V_{DD}DOK COMPARATORS	МАХ	UNITS
egative Output Voltage Range $V_{DD} = 5.5V$ (Note 1)-9aximum Output Current $V_{IN} = 4.5V$, $V_{OUT+} \ge 14.25V$, $V_{OUT-} \le -7.125V$, Figure 310le Quiescent CurrentSYNC = GND10AUTDOWNnutdown Supply CurrentSYNC = SEQ = SHDN = GNDNDERVOLTAGE LOCKOUT/LO Threshold V_{DD} = rising2.35BIPUTS AND REFERENCE VOLTAGE3P Threshold VoltageNo load1.2053N Threshold VoltageNo load-20REF Output VoltageNo load1.225OGIC INPUTS (SEQ, SHDN, SYNC)2.7V < $V_{DD} \le 5.5V$ 0.7 x V_{DD} ogic-Low Input2.7V < $V_{DD} \le 5.5V$ 0.7 x V_{DD} COMPARATORS	5.5	V
aximum Output Current $V_{IN} = 4.5V, V_{OUT+} \ge 14.25V, V_{OUT-} \le -7.125V,$ Figure 310le Quiescent CurrentSYNC = GNDHUTDOWNnutdown Supply CurrentSYNC = SEQ = SHDN = GNDNDERVOLTAGE LOCKOUT/LO Threshold V_{DD} = rising2.352.35BIPUTS AND REFERENCE VOLTAGE3P Threshold VoltageNo load3N Threshold VoltageNo load3N Threshold VoltageNo load4EF Output VoltageNo load3EF Output VoltageNo load1.225DGIC INPUTS (SEQ, SHDN, SYNC)rigic-Low Input2.7V < V_DD ≤ 5.5V	24	V
Figure 3IUIde Quiescent CurrentSYNC = GNDHUTDOWNHUTDOWNHUTDOWNHUTDOWNHUTDOWNHUTOOWNNDERVOLTAGE LOCKOUTVLO Threshold V_{DD} = rising2.35BINPUTS AND REFERENCE VOLTAGEBP Threshold VoltageNo load3N Threshold VoltageNo load3N Threshold VoltageNo load2.20BEF Output VoltageNo load2.7V < VDD ≤ 5.5V	-1.27	V
HUTDOWNhutdown Supply CurrentSYNC = SEQ = SHDN = GNDNDERVOLTAGE LOCKOUTVDD = rising2.35VLO ThresholdVDD = rising2.35B INPUTS AND REFERENCE VOLTAGE381.20538 Threshold VoltageNo load1.20539 Threshold VoltageNo load-2039 Threshold VoltageNo load1.225OGIC INPUTS (SEQ, SHDN, SYNC) $2.7V < VDD \le 5.5V$ $0.7 \times VDD$ Ogic-High Input $2.7V < VDD \le 5.5V$ $0.7 \times VDD$		mA
Nutdown Supply CurrentSYNC = SEQ = SHDN = GNDNDERVOLTAGE LOCKOUTVDD = rising2.35VLO ThresholdVDD = rising2.35B PUTS AND REFERENCE VOLTAGE1.2053P Threshold VoltageNo load1.2053N Threshold VoltageNo load-20REF Output VoltageNo load1.225OGIC INPUTS (SEQ, SHDN, SYNC) $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$ Degic-High Input $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$	500	μA
NDERVOLTAGE LOCKOUT/LO Threshold V_{DD} = rising2.353 INPUTS AND REFERENCE VOLTAGE3P Threshold VoltageNo load1.2053P Threshold VoltageNo load-203R Threshold VoltageNo load-203EF Output VoltageNo load1.225OGIC INPUTS (SEQ, SHDN, SYNC)ogic-Low Input2.7V < V_DD ≤ 5.5V		
VLO Threshold $V_{DD} = rising$ 2.35S INPUTS AND REFERENCE VOLTAGE3P Threshold VoltageNo load1.2053N Threshold VoltageNo load-203R F Output VoltageNo load1.225DGIC INPUTS (SEQ, SHDN, SYNC) $2.7V < V_{DD} \le 5.5V$ 0.7 x V_{DD}Dgic-High Input $2.7V < V_{DD} \le 5.5V$ 0.7 x V_{DD}	10	μA
Boo and a second secon		
BP Threshold VoltageNo load1.205BN Threshold VoltageNo load-20REF Output VoltageNo load1.225OGIC INPUTS (SEQ, SHDN, SYNC) $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$ ogic-High Input $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$ OK COMPARATORS V V	2.65	V
BN Threshold VoltageNo load-20BN Threshold VoltageNo load-20REF Output VoltageNo load1.225DGIC INPUTS (SEQ, SHDN, SYNC) $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$ pgic-Low Input $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$ DK COMPARATORS $0.7 \times V_{DD}$ $0.7 \times V_{DD}$		
REF Output VoltageNo load1.225OGIC INPUTS (SEQ, SHDN, SYNC)agic-Low Input $2.7V < V_{DD} \le 5.5V$ agic-High Input $2.7V < V_{DD} \le 5.5V$ OK COMPARATORS	1.275	V
DGIC INPUTS (SEQ, SHDN, SYNC)ogic-Low Input $2.7V < V_{DD} \le 5.5V$ ogic-High Input $2.7V < V_{DD} \le 5.5V$ OK COMPARATORS	40	mV
bgic-Low Input $2.7V < V_{DD} \le 5.5V$ bgic-High Input $2.7V < V_{DD} \le 5.5V$ $0.7 \times V_{DD}$ DK COMPARATORS $0.7 \times V_{DD}$ $0.7 \times V_{DD}$	1.275	V
Ogic-High Input 2.7V < V _{DD} ≤ 5.5V 0.7 × V _{DD} OK COMPARATORS Image: Comparison of the second		
DK COMPARATORS	$0.3 \times V_{DD}$	V
		V
DDDO// Threadhold DDD riving 1 000		L
3P POK Threshold FBP rising 1.090	1.150	V
3N POK Threshold FBN falling 54	108	mV

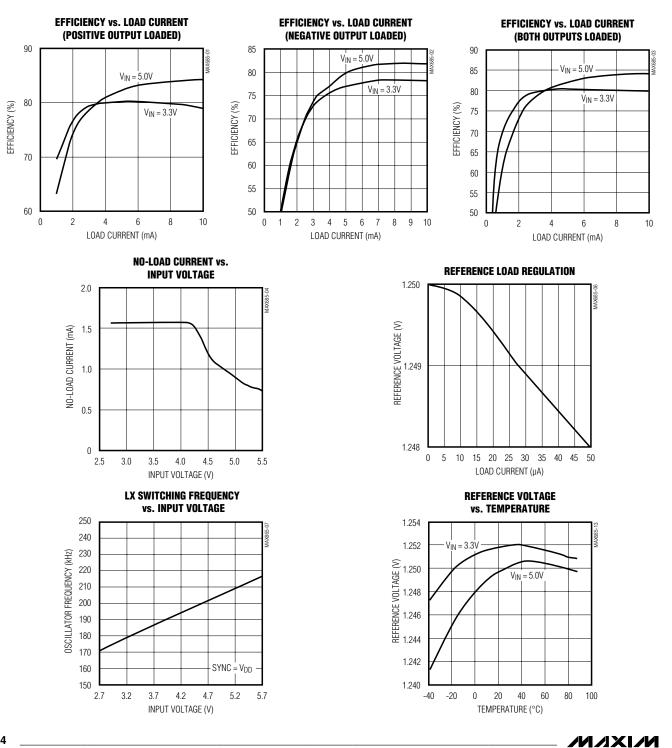
Note 1: Negative output voltage can be larger magnitude for lower values of V_{DD} . The voltage between V_{DD} and V_{OUT} - must not exceed 14.5V.

Note 2: Specifications to -40°C are guaranteed by design, not production tested.

M/IXI/M

MAX685

(Circuit of Figure 3, V_{OUT+} = 15V, V_{OUT-} = -7.5V, T_A = +25°C, unless otherwise noted.)



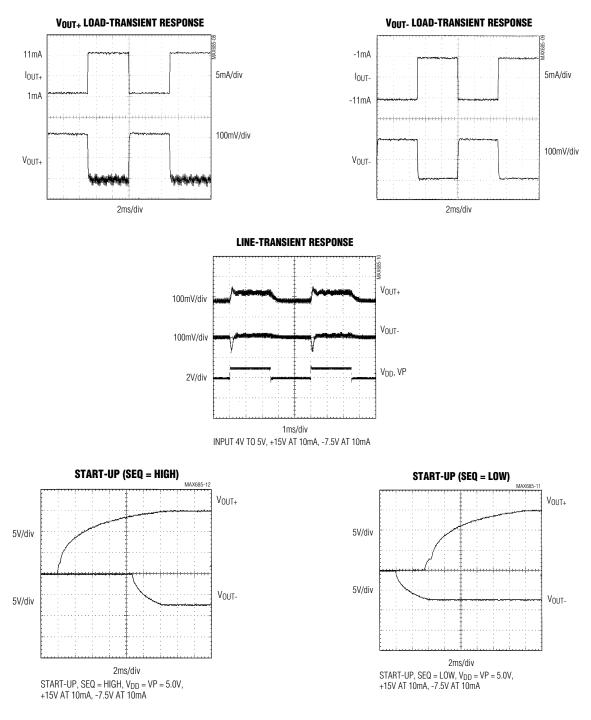
Typical Operating Characteristics

MAX685

4

Typical Operating Characteristics (continued)

(Circuit of Figure 3, $V_{OUT+} = 15V$, $V_{OUT-} = -7.5V$, $T_A = +25^{\circ}C$, unless otherwise noted.)



MAX685

M/IXI/M

Pin Description

PIN 16-QSOP	PIN 24-TQFN	NAME	FUNCTION
1	22, 23	LXP	P-Channel Switching Inductor Node. LXP turns off when the part enters shutdown.
2, 15	19, 24	I.C.	Internally Connected. Do not externally connect.
3	2, 3	VP	Power Input. Connect to V _{DD} .
4	4	POK	Open-Drain Power-OK Output. POK is high when both outputs are in regulation. Connect POK to V_{DD} with a 100k Ω pull-up resistor to V_{DD} .
5	5	SEQ	Power-Up Sequence Select Input. Connect SEQ to GND to power the negative output voltage first. Connect SEQ to V_{DD} to power the positive output first.
6	6	SHDN	Shutdown Input. Both outputs go to 0V in shutdown. Connect to V_{DD} for automatic startup.
7	7	SYNC	Sync Input. This pin synchronizes the oscillator to an external clock frequency between 200kHz and 480kHz. Connect SYNC to GND (220kHz) or V_{DD} (400kHz) for internal oscillator frequency.
8	8	V _{DD}	Supply Input. Bypass V _{DD} with a 1.0µF or greater ceramic capacitor to GND.
9	11	GND	Ground
10	12	FBN	Feedback Input for the Negative Output Voltage. Connect a resistor-divider between the nega- tive output and REF with the center to FBN to set the negative output voltage.
11	13	REF	1.25V Reference Voltage Output. Bypass with 0.22µF to GND.
12	14	FBP	Feedback for the Positive Output Voltage. Connect a resistor-divider between the positive out- put and GND with the center to FBP to set the positive output voltage.
13, 14	15, 16, 17	PGND	Power Ground. Connect PGND to GND.
16	20, 21	LXN	N-Channel Switching Inductor Node. LXN pulls to GND through the internal transistor when the part is shut down.
	1, 9, 10, 18	N.C.	This pin in not internally connected.

Detailed Description

The MAX685 DC-DC converter accepts an input voltage between +2.7V and +5.5V and generates both a positive and negative voltage, using a single inductor (Figure 1). It alternates between acting as a step-up converter and as an inverting converter on a cycle-by-cycle basis. Both output voltages are independently regulated.

Each output is separately controlled by a pulse-widthmodulated (PWM) current mode regulator. This allows the part to operate at a fixed frequency for use in noisesensitive applications. An internal oscillator runs at 220kHz or 400kHz, or can be synchronized to an external signal. Since switching alternates between the two regulators, each operates at half the oscillator frequency (110kHz, 200kHz, or half the sync frequency). The oscillator can be synchronized to a 200kHz to 480kHz clock. On the first cycle of operation, the part operates as a step-up converter. LXP connects to V_{DD}, LXN pulls to ground, and the inductor current rises. Once the inductor current rises to a level set by the positive-side error amplifier, LXN releases and the inductor current flows through D2 to the positive output. When the inductor current drops to zero (which happens each cycle under normal, discontinuous operation), LXN returns to the input voltage.

On the second cycle, LXN is held at ground. LXP is pulled up to the input voltage until the current reaches the limit set by the negative error amplifier. Then LXP is released and the inductor current flows through D1 to the negative output. Once the inductor current reaches zero, the voltage at LXP returns to ground. The waveforms at LXN and LXP are shown in Figure 2 for a typical pair of cycles.



MAX685

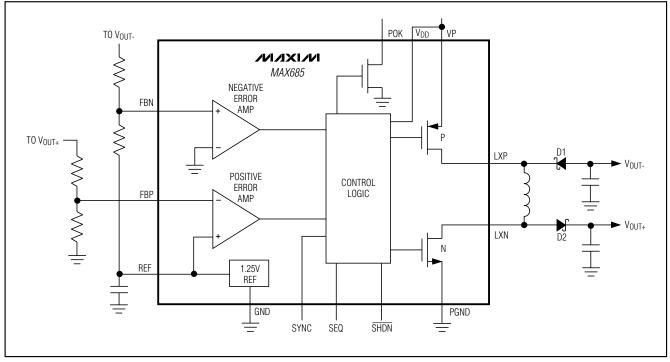


Figure 1. Functional Diagram

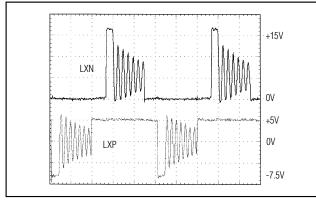


Figure 2. LXN and LXP Waveforms (see also Figure 5)

The current into the LXN pin is sensed to measure the inductor current. The MAX685 controls the inductor current to regulate both the positive and negative output voltages.

SEQ and Power OK (POK)

The SEQ pin controls the power-up sequence. If SEQ is low, the positive output is disabled until the negative output is within 90% of its regulation point. If SEQ is high, the negative output is disabled until the positive



output is within 90% of its regulation point. The power-OK output (POK) indicates that both output voltages are in regulation. When both outputs are within 90% of their regulation points, POK becomes high impedance. Should one or both of the output voltages fall below 90% of their regulation points, POK pulls to ground. POK can sink up to 2mA. To reduce current consumption, POK is high impedance while the part is in shutdown. When coming out of shutdown, POK remains high impedance for 50ns (typ) before going low. Connect POK to V_{DD} through a 100k Ω resistor.

Synchronization/Internal Frequency Selection

The MAX685 operates at a fixed switching frequency. Set the operating frequency using the SYNC pin. If SYNC is grounded, the part operates at the internally set 220kHz frequency. When SYNC is connected to V_{DD}, the part operates at 400kHz. The MAX685 can also be synchronized to signals between 200kHz and 480kHz. Note that each output switches at half the oscillator or synchronized frequency. Since the actual switching frequency is one-half the applied clock signal, drive SYNC at twice the desired switching frequency.

MAX685

Applications Information

Figure 3 shows the standard application circuit for the MAX685. The values shown in Table 1 will work well for output currents up to 10mA. However, this circuit can be optimized to a particular application by using different capacitors and a different inductor.

Higher Output Voltages

If the application requires output voltages greater than -7.5V or +24V, use the circuit of Figure 4. This circuit uses a charge pump to increase the output voltage without increasing the voltage stress on the LX_ pin. The maximum output voltages of the circuit in Figure 4 are -15V and +48V.

The voltage rating on D2, D5, and D6 must be 30V or greater. For a larger negative output voltage without a larger positive output (or vice versa), use one-half of the Figure 4 circuit with one-half of the Figure 3 circuit.

Inductor Selection

A 22µH inductor is suitable for most applications. Larger inductances will reduce inductor ripple current and output voltage ripple, but they also typically require larger physical size if increased resistance and losses are not also allowed. Small inductors are typically preferred because of compact design and low cost. Murata LHQ and TDK NLC types are examples of small surface-mount inductors that work for most applications. Because these small-size inductors use thinner wire, they exhibit higher resistance and have greater losses than larger ones. If the application demands higher efficiency, use larger, lower resistance coils such as the Sumida CD43 or CD54, Coilcraft DT1608 or DO1608, or Coiltronics UP1V series.

Filter Capacitor Selection

The output ripple voltage is a function of the peak inductor current, frequency, and type and value of the output capacitors. Capacitors with low equivalentseries resistance (ESR) and large capacitance reduce output ripple. Typically, tantalum or ceramic capacitors are optimal. Tantalum capacitors have higher ESR and higher capacitance than ceramic capacitors. Therefore the ESR of tantalum capacitors determines the output ripple, because at the frequencies used the ESR dominates the impedance of the capacitor. If ceramic capacitors are used, the capacitance determines the output ripple.

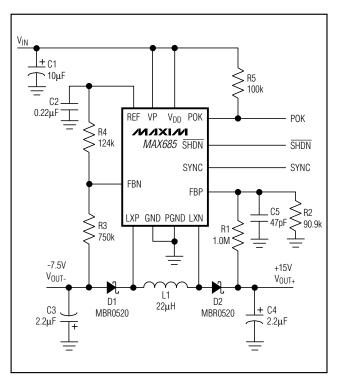


Figure 3. Standard Application Circuit

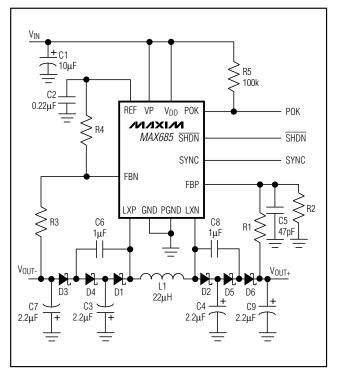


Figure 4. Circuit for Output Voltages < -9V and > +24V

Table 1. Component Values for theTypical Operating Circuit

REF	DESCRIPTION	MANUFACTURER PART NUMBER
C1	10µF, 10V tantalum cap	Sprague 595D106X0010A2T or AVX TAJA106K010R
C2	0.22µF ceramic capacitor	Any manufacturer
C3, C4	2.2µF ceramic capacitor	Any manufacturer
C5	47pF ceramic cap	Any manufacturer
D1, D2	0.1A, 20V Schottky rectifier	Motorola MBR0520LT1 (0.5A) or Central Semiconductor CMPSH-3
L1	22µH, 0.4A inductor	Murata LHQ4N220J04 or TDK NLC32522T-220K

Setting the Output Voltage

The resistor-divider formed by R4 and R3 sets the negative output voltage; the resistor-divider formed by R1 and R2 sets the positive output voltage. Let R4 be a value near 100k Ω to set a resistor-divider current of approximately 10µA. Determine the value of R3 by the following:

$$R3 = R4 \frac{|V_{OUT-}|}{1.24V}$$

Let R2 be a value near $100k\Omega$ to set a resistor-divider current of approximately $10\mu A$. Determine the value of R1 with the following formula:

$$R1 = R2 \times (V_{OUT} + - 1.24V) / 1.24$$

Damping LX

LXN and LXP may ring at the conclusion of each switching cycle when the inductor current falls to zero. Typically the ringing waveform appears only on LX_ and has no effect on output ripple and noise. If LX_ ringing is still objectionable, it may be damped by connecting a series RC in parallel with L1. Typically 1k Ω in series with 100pF provides good damping with only 3% efficiency degradation. See Figure 5.

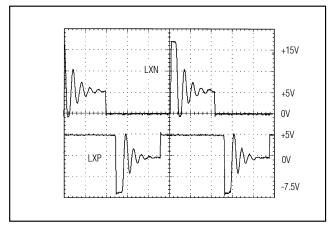


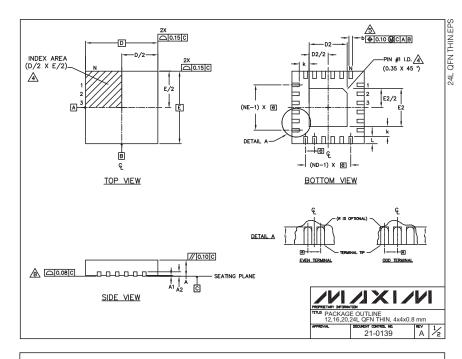
Figure 5. LXN and LXP Waveforms with a Series-Connected 1k Ω Resistor and 100pF Capacitor Connected in Parallel with L1 to Damp Ringing

Chip Information

TRANSISTOR COUNT: 902 SUBSTRATE CONNECTED TO GND

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <u>www.maxim-ic.com/packages</u>.

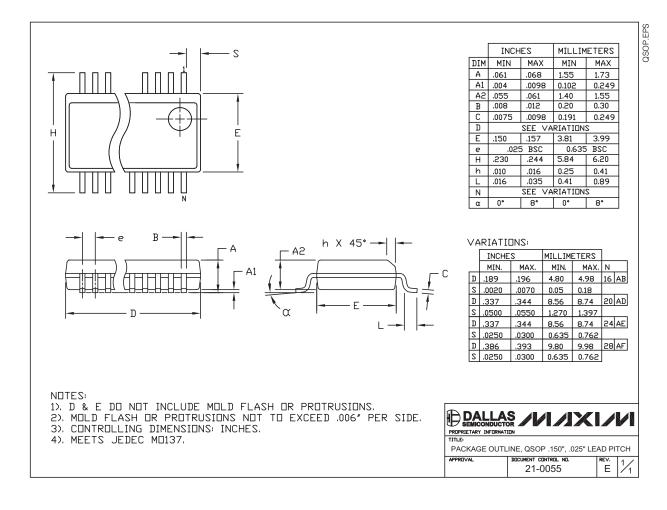


					COMM	IN DI	MENS	SIONS					EXP	DSED	PAD	VAF	ITAIS	[DNS	
PKG	1	2L 4×4	F .	1	6L 4×4		2	20L 4×4	4	é	24L 4×	4	PKG.		D2			E2	
REF.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	CODES	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	T1244-2	1.95	2.10	2.25	1.95	2.10	2.25
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	T1644-2	1.95	2.10	2.25	1.95	2.10	2.25
A2		0.20 REF			0.20 REF			0.20 REF			0.20 REF		T2044-1	1.95	2.10	2.25	1.95	2.10	2.25
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	T2444-1	2.45	2.60	2.63	2.45	2.60	2.63
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10							
E	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10							
e	-	0.80 BSC			0.65 BSC			0.50 BSC	1		0.50 BSC	<u></u>							
k	0.25	0.55	- 0.65	0.25	- 0.55	- 0.65	0.25	- 0.55	- 0.65	0.25	0.40	- 0.50							
N	0.40	12	0.63	0.40	16	0.60	0.40	20	1 0.63	0.30	24	0.50							
ND	-	3			4			5			6								
NE	-	3			4			5			6								
		-						VGGD-			WGGD-	2							
NOTES:		WGGB			WGGC		<u> </u>		-		<u>- 400</u>	<u> </u>							
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Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <u>www.maxim-ic.com/packages</u>.)



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